

L37-5S 導熱矽膠 Thermal Pad



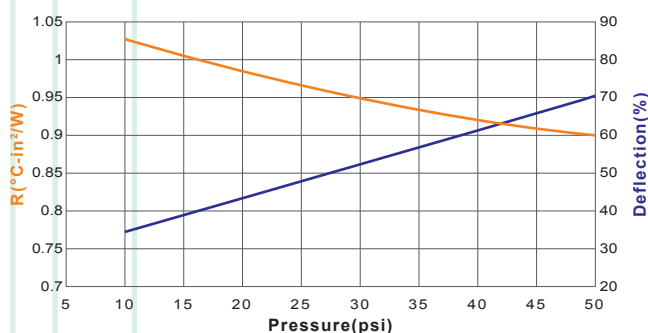
產品特性 Features

Best for filling the gap 適用於間隙填補
Compliancy, high compressibility 高壓縮性
Ultra soft, low hardness (Shore 00) 超低硬度非常柔軟
Lower pressure to heated components or PCB
可緩衝降低其對發熱元件或印刷版的壓力

產品應用端 Applications

Electronic components: IC, CPU, MOS
LED, M/B, P/S, Heat Sink,
LCD-TV, Notebook PC, PC, Telecom Device, Wireless Hub.....etc
DDR II Module, DVD Applications, Hand-set applications.....etc

熱阻抗VS.壓力VS.變形量示意圖 Thermal Resistance VS. Pressure VS. Deflection

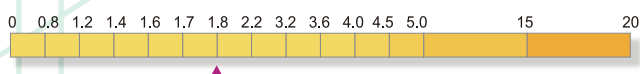


Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	1.03	35
30	0.95	52
50	0.9	70

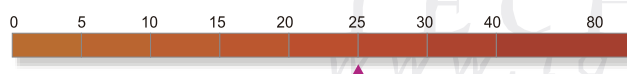
產品物性 Properties

REACH Compliant 符合REACH規範 RoHS Compliant 符合RoHS規範 UL Compliant 符合UL規範

Thermal Conductivity 導熱係數 : 1.8 W/mK



Hardness 軟硬度 : 25 (Shore 00)



Testing sample thickness: 1.0mm

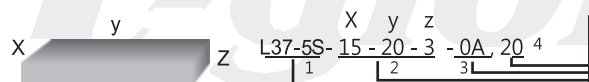
In "Thermal resistance V.S. Pressure V.S. Deflection" chart, L37-5S provides low thermal impedance. The pressure gets higher, the thermal impedance gets lower, and deflection percentage gets higher. L37-5S provides good compliance and softness.

Properties	L37-5S	Unit	Tolerance	Test Method
Thermal Conductivity 導熱係數	1.8	W / mK	±0.18	ASTM D5470
Thickness 厚度	0.5~5.0	mm	-	ASTM D374
	0.0197~0.1969	inch	-	ASTM D374
Color 顏色	Gray灰	-	-	Visual目視
Flame Rating耐燃等級	V-0	-	-	UL 94
Dielectric Breakdown Voltage耐電壓	16	KV / mm	±1.6	ASTM D149
Weight Loss重量損失	<1	%	-	ASTM E595
Specific Gravity比重	2.4	g / cm³	±0.2	ASTM D792
Working Temperature工作溫度	-45~+200	°C	-	-
Volume Resistance體積阻抗	>10 ¹²	Ohm-cm	-	ASTM D257
Elongation延展率	300	%	-	ASTM D412
Tensile Strength抗拉強度	1	Kgf / cm²	-	ASTM D412
Standard Shape標準形狀	Sheet ones單片狀	-	-	-
Hardness硬度	25	Shore 00	±10	ASTM D2240

Need samples? 樣品需求?

Available to apply adhesive 可依需求背膠

Pre-cut for different shapes 可依需求沖型裁切



1. Choose the P/N
2. Fill into size: x,y,z
3. Fill the quantity you need